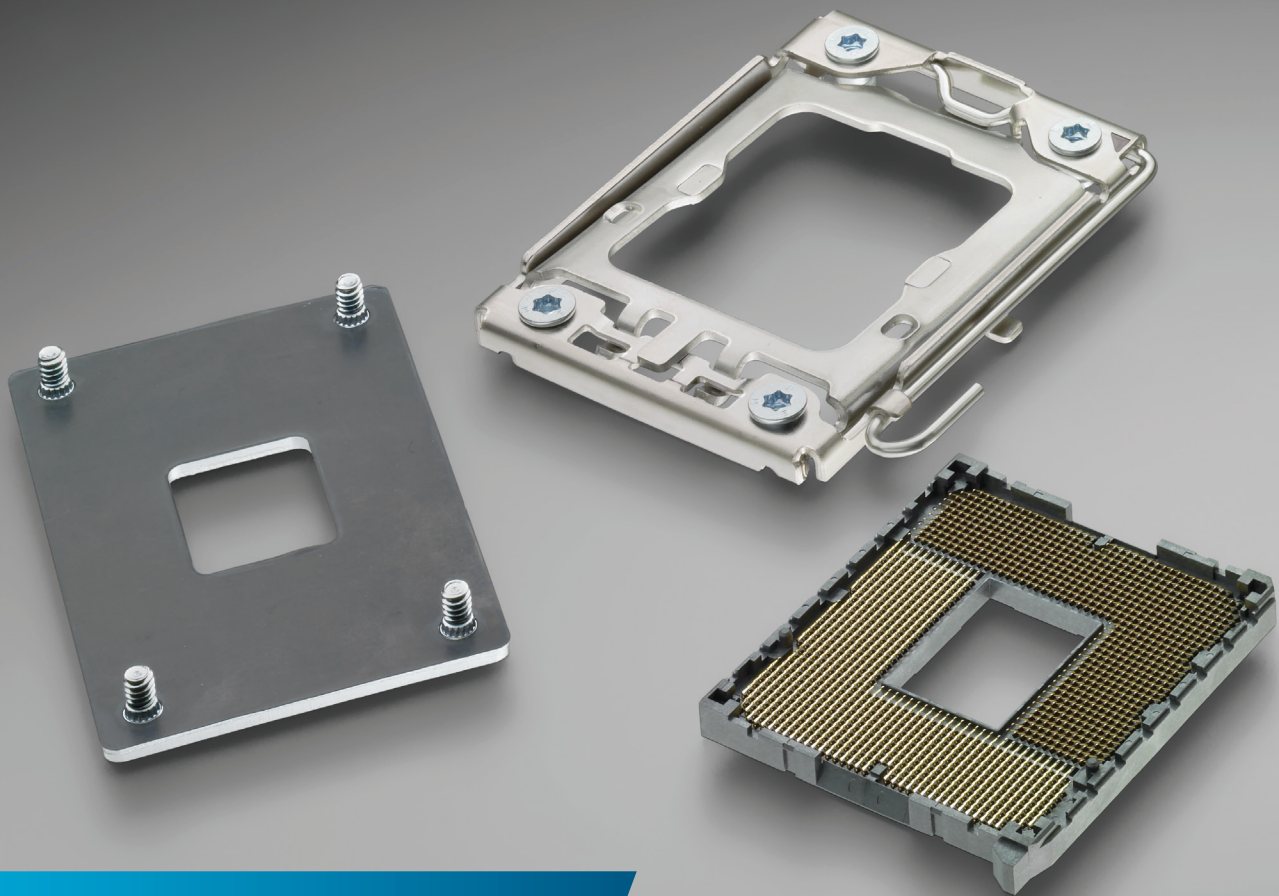
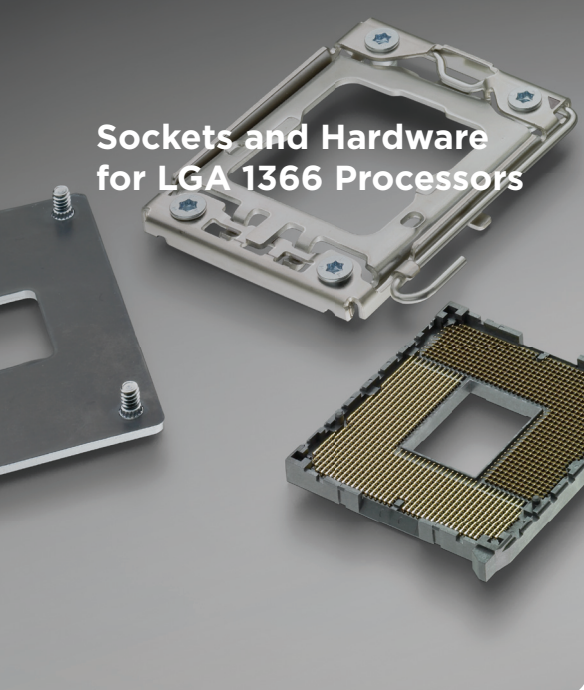




Introducing Sockets and Hardware for LGA 1366 Processors

Tyco Electronics' surface mount LGA socket was designed for use with Intel's® Core™ i7 LGA 1366 processor. The contacts have .64mm diameter solder balls for surface mount onto the PCB, while the top side provides a cantilever beam interface to the package. The integrated lever mechanism (ILM) generates the Z-axis compression load. A robust bolster plate helps eliminate PCB bowing during compression. The sockets are validated to Intel Design Guides.

Sockets and Hardware for LGA 1366 Processors



KEY FEATURES

- 1366 contacts with a 1.016mm x 1.016mm grid.
- Available with 15 or 30 Gold contact plating.
- Socket housing facilitates efficient soldering to the PCB board.
- Socket is supplied with a cap to facilitate vacuum pick and place. Spare caps can be ordered separately.
- Two backplate options for use in desktop or server applications.
- ILM and backplate must be ordered separately. Kits are also available for ease in ordering.

Tyco Electronics Corporation Technical Support Center

Internet: www.tycoelectronics.com/help

USA: +1 (800) 522-6752

Canada: +1 (905) 470-4425

Central America
& Mexico +52 (0) 55-1106-0814

South America: +55 (0) 11-2103-6000

Germany: +49 (0) 6251-133-1999

UK: +44 (0) 8706-080208

France: +33 (0) 1-3420-8686

Netherlands: +31 (0) 73-6246-999

China: +86 (0) 400-820-6015

www.tycoelectronics.com

© 2009 Tyco Electronics Corporation. All Rights Reserved.

3-1773455-9 CIS-MS-10/2009

TE (logo) and Tyco Electronics are trademarks of the Tyco Electronics

group of companies and its licensors.

Other products, logos, and company names mentioned herein may be trademarks of their respective owners.

APPLICATIONS

- Servers
- High End desktop computers

ELECTRICAL

- Low level bulk contact resistance: 15 milliohms max avg.
- Insulation resistance: 800 milliohms min. @ 500 VDC

MECHANICAL

- Nominal Deflection: .5 mm
- Durability: 30 cycles
- Mating and Unmating force of Lever: 49N max

MATERIALS

- Socket assembly
Contact: Copper Alloy, gold plating on contact area over nickel plating.
Base housing: Thermoplastic UL94V-0
Cap: Thermoplastic UL94V-0
- ILM load plate and lever: Stainless steel
- ILM frame, nut and collar: Steel
- Backplate assembly: Steel
- Insulator: Polypropylene

APPLICATIONS AND SPECIFICATION

- Application specification 114-5432
- Product specification 108-78496

PRODUCT OFFERINGS

Part Number	Description	Plating	Solder Ball
1981837-1	LGA 1366 Socket	15 Gold	Lead Free
1981837-2	LGA 1366 Socket	30 Gold	Lead Free
1-1981837-2	LGA 1366 Socket	30 Gold	Leaded
1939738-1	ILM U Lever		
1-1939738-2	ILM Straight Lever		
1-1939738-1	Short Straight Lever		
1939739-1	Desktop Back Plate		
1981467-1	Server Back Plate		
1-1981374-1	Spare socket cap		

ILM/Back Plate Kits

Part No.	1939738-1 U Lever	1-1939738-2 Straight Lever	1-1939738-1 Short Straight Lever	1939739-1 Desktop Back Plate	1981467-1 Server Back Plate
2040865-1	1			1	
2040865-2	1				1
2040865-3		1		1	
2040865-4		1			1
2040865-9			1	1	
1-2040865-0			1		1

 **Tyco Electronics**

Our commitment. Your advantage.

While Tyco Electronics has made every reasonable effort to ensure the accuracy of the information in this catalog, Tyco Electronics does not guarantee that it is error-free, nor does Tyco Electronics make any other representation, warranty or guarantee that the information is accurate, correct, reliable or current. Tyco Electronics reserves the right to make any adjustments to the information contained herein at any time without notice. Tyco Electronics expressly disclaims all implied warranties regarding the information contained herein, including, but not limited to, any implied warranties of merchantability or fitness for a particular purpose. The dimensions in this catalog are for reference purposes only and are subject to change without notice. Specifications are subject to change without notice. Consult Tyco Electronics for the latest dimensions and design specifications.